



Automatic Large Area Bond Tester 8600C

Bond System

Test heads Pullheads – 100 cN, 1000 cN, 5000 cN
Shearheads – 500 cN, 5000 cN

Machine Base

Table travel X=700 mm, Y=480 mm, Z=100 mm
Resolution 1 µm, repeatability 5 µm

Speed All axes programmable from 0.2 to 16 mm/s
Test speed from 0.2 to 5 mm/s

Measurement heads

Accuracy 0.25% of maximum value

Calibration Stored in measurement head, temperature-compensated load cell
Optional calibration at customer's side (Specific tools)

Control

Computer Dual Core PC, Ethernet, USB 2.0/3.0
GigE-CCD-Colour Camera,
fully networkable in TCP/IP server

Monitor TFT flat screen monitor 22"

Printer all Windows-compatible printers can be installed

8600C:

The automatic bond tester 8600C complements F&S Bondtec Semiconductor GmbH die- and wire-bonders.

The PC controlled axis allows any number of bonds to be tested automatically from a stored program on a large area (eg. for Battery-, Solar-application, etc.).

Results can be analysed and output immediately or exported in a number of data base formats for subsequent analysis.

Powerful extended capabilities enable measurements such as force/time curves deliver more data about the quality of the bond tested.

Exchangeable measurement cartridges ensure rapid conversion to different force ranges.

Additional features

| | |
|----------------------|---|
| Programming | Automatic repeat measurements on hybrids or COB using the programmable head movement and Pattern Recognition Unit (PRU) |
| Evaluation | Statistics such as mean value, standard deviation, trend, cpk, etc. Based on SQL Databank |
| Export format | SQL, CSV, HTML |
| Other | Operator profile, various password levels, optional barcode readers for product Identification; feedback of measured values to die and wire bonders for parameter optimisation optional |

General

| | |
|--------------------|---|
| Microscope | Stereoscope Olympus, other microscopes optional |
| Dimensions | approx. height 200cm, width 130cm, depth 100cm, approx. 700kg |
| Supplies | 230 VAC, |
| Connections | Air 6 bar; vacuum 0,7 bar |

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